

Laura Spinella

List of Publications by Year in descending order

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Version: 2024-02-01

13
papers

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citations

1307594

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1588992

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g-index

13
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docs citations

13
times ranked

141
citing authors

#	ARTICLE	IF	CITATIONS
1	Electrochemical degradation modes in bifacial silicon photovoltaic modules. Progress in Photovoltaics: Research and Applications, 2022, 30, 948-958.	8.1	11
2	Chemical and mechanical interfacial degradation in bifacial glass/glass and glass/transparent backsheets photovoltaic modules. Progress in Photovoltaics: Research and Applications, 2022, 30, 1423-1432.	8.1	8
3	Thermomechanical fatigue resistance of low temperature solder for multiwire interconnects in photovoltaic modules. Solar Energy Materials and Solar Cells, 2021, 225, 111054.	6.2	10
4	Reliability Implications of Solder in Multiwire Modules under Dynamic Mechanical Loading. , 2021, , .		1
5	Glass/glass photovoltaic module reliability and degradation: a review. Journal Physics D: Applied Physics, 2021, 54, 413002.	2.8	34
6	UV-Fluorescence Imaging of Silicon PV Modules After Outdoor Aging and Accelerated Stress Testing. , 2020, , .		5
7	Synchrotron X-Ray Microdiffraction Investigation of Scaling Effects on Reliability for Through-Silicon Vias for 3-D Integration. IEEE Transactions on Device and Materials Reliability, 2019, 19, 568-571.	2.0	10
8	FTIR Investigation of EVA Chemical Bonding Environment and Its Impact on Debond Energy. IEEE Journal of Photovoltaics, 2019, 9, 790-795.	2.5	10
9	Application of Electronics Packaging Fundamentals to Photovoltaic Interconnects and Packaging. , 2019, , .		0
10	Microstructure Evolution and Effect on Resistivity for Cu Nanointerconnects and Beyond. , 2018, , .		6
11	Microstructure Evolution and Implications for Cu Nanointerconnects and Beyond. , 2018, , .		0
12	Processing Effect on Via Extrusion for TSVs in Three-Dimensional Interconnects: A Comparative Study. IEEE Transactions on Device and Materials Reliability, 2016, 16, 465-469.	2.0	7
13	Plasticity mechanism for copper extrusion in through-silicon vias for three-dimensional interconnects. Applied Physics Letters, 2013, 103, .	3.3	57